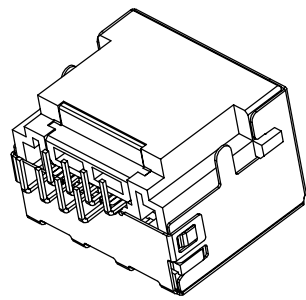
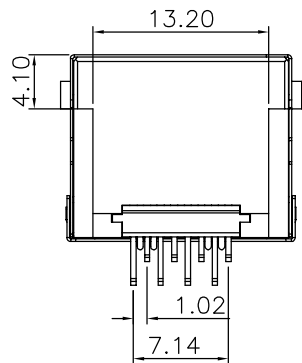
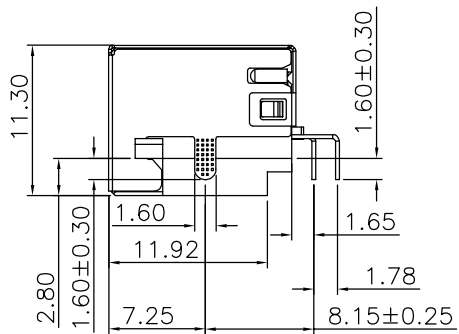
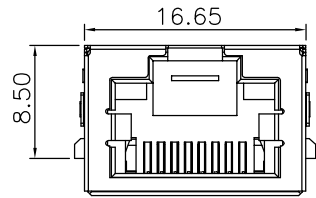
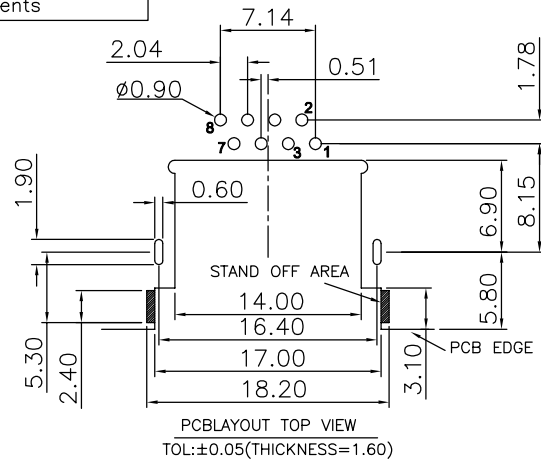
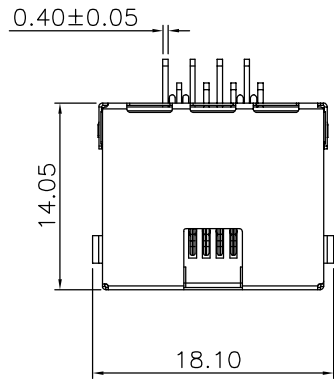


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements



NOTE:
 1.MATERIAL SPECIFICATION:
 1-1.HOUSING: LCP UL94V-0
 1-2.SHELL: 0.20mm COPPER ALLOY
 1-3.CONTACT: COPPER ALLOY T=0.30MM
 2.PLATING SPECIFICATION:
 GOLD PLATING OVER NI
 100u"SN PLATED ON SOLDER TALL AREA
 50u"NI UNDER PLATED OVER ALL
 2-1.SHELL:
 Ni 30U" MIN PLATING OVER ALL
 3.MECHANICAL PERFORMANCE:
 3-1.INSERTION FORCE: 22N MAX
 3-2.REMOVAL FORCE: 22N MAX
 3-2.DURABILITY: 750 CYCLES MIN.
 4.ELECTRICAL PERFORMANCE:
 4-1.CURRENT RATING:1.5A
 4-2.VOLTAGE RATING:125V MAX
 4-3.CONTACT RESISTANCE: 40mΩ Max.
 4-4.INSULATION RESISTANCE: 500MΩ MIN
 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC Min
 5.ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -40°C~+85°C.
 6.PACKAGE SPEC:TRAY

P/N:
 WLR4F9-08 8 X X X 028

PLATING: 1-G/F
 2-Au 3u"
 3-Au 6u"
 5-Au 15u"
 6-Au 30u"
 HOUSING: 1-PBT
 2-LCP
 3-PA9T
 COLOUR: A-BLACK

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	21.01.13	WLR4F9-088XXX028	ENDE05	
			UNIT:mm	0.00±0.25	X°±3°	DESIGNER	Han_Gao	21.01.13	TITLE:		REV: A0 SHEET: 1/1
			SIZE: A4	0.000±0.10	X°X' ±2°	DRAWN	Zijun_Huang	21.01.13	RJ45 8P8C DIP沉板式2.8MM		